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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, Temp Sensor, WDT
Number of I/O	17
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	64 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f022ash020sc00tr

Table 2. Signal Descriptions (Continued)

Signal Mnemonic	I/O	Description
Analog		
ANA[7:0]	I	Analog Port. These signals are used as inputs to the analog-to-digital converter (ADC).
VREF	I/O	Analog-to-digital converter reference voltage input, or buffered output for internal reference.
Low-Power Operational Amplifier (LPO)		
AMPINP/AMPINN	I	LPO inputs. If enabled, these pins drive the positive and negative amplifier inputs respectively.
AMPOUT	O	LPO output. If enabled, this pin is driven by the on-chip LPO.
Oscillators		
XIN	I	External Crystal Input. This is the input pin to the crystal oscillator. A crystal can be connected between it and the **XOUT** pin to form the oscillator. In addition, this pin is used with external RC networks or external clock drivers to provide the system clock.
XOUT	O	External Crystal Output. This pin is the output of the crystal oscillator. A crystal can be connected between it and the **XIN** pin to form the oscillator.
Clock Input		
CLKIN	I	Clock Input Signal. This pin may be used to input a TTL-level signal to be used as the system clock.
LED Drivers		
LED	O	Direct LED drive capability. All port C pins have the capability to drive an LED without any other external components. These pins have programmable drive strengths set by the GPIO block.
On-Chip Debugger		
DBG	I/O	Debug. This signal is the control and data input and output to and from the On-Chip Debugger. **Caution:** *The DBG pin is open-drain and requires a pull-up resistor to ensure proper operation.*
Reset		
$\overline{\text{RESET}}$	I/O	RESET. Generates a Reset when asserted (driven Low). Also serves as a reset indicator; the Z8 Encore! XP forces this pin low when in reset. This pin is open-drain and features an enabled internal pull-up resistor.

mation Area data rather than the Program Memory data. Access to the Flash Information Area is read-only.

Table 6. Z8 Encore! XP F082A Series Flash Memory Information Area Map

Program Memory Address (Hex)	Function
FE00–FE3F	Zilog Option Bits/Calibration Data
FE40–FE53	Part Number 20-character ASCII alphanumeric code Left justified and filled with FFH
FE54–FE5F	Reserved
FE60–FE7F	Zilog Calibration Data
FE80–FFFF	Reserved

GPIO Interrupts

Many of the GPIO port pins can be used as interrupt sources. Some port pins can be configured to generate an interrupt request on either the rising edge or falling edge of the pin input signal. Other port pin interrupt sources generate an interrupt when any edge occurs (both rising and falling). See Interrupt Controller on page 55 for more information about interrupts using the GPIO pins.

GPIO Control Register Definitions

Four registers for each Port provide access to GPIO control, input data, and output data. Table 16 lists these Port registers. Use the Port A–D Address and Control registers together to provide access to sub-registers for Port configuration and control.

Table 16. GPIO Port Registers and Sub-Registers

Port Register Mnemonic	Port Register Name
P*x*ADDR	Port A–D Address Register (Selects sub-registers)
P*x*CTL	Port A–D Control Register (Provides access to sub-registers)
P*x*IN	Port A–D Input Data Register
P*x*OUT	Port A–D Output Data Register
Port Sub-Register Mnemonic	**Port Register Name**
P*x*DD	Data Direction
P*x*AF	Alternate Function
P*x*OC	Output Control (Open-Drain)
P*x*HDE	High Drive Enable
P*x*SMRE	Stop Mode Recovery Source Enable
P*x*PUE	Pull-up Enable
P*x*AFS1	Alternate Function Set 1
P*x*AFS2	Alternate Function Set 2

PIN[7:0]—Port Input Data
Sampled data from the corresponding port pin input.
0 = Input data is logical 0 (Low).
1 = Input data is logical 1 (High).

Port A–D Output Data Register

The Port A–D Output Data register (Table 28) controls the output data to the pins.

Table 28. Port A–D Output Data Register (P*x*OUT)

BITS	7	6	5	4	3	2	1	0
FIELD	POUT7	POUT6	POUT5	POUT4	POUT3	POUT2	POUT1	POUT0
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ADDR	FD3H, FD7H, FDBH, FDFH							

POUT[7:0]—Port Output Data
These bits contain the data to be driven to the port pins. The values are only driven if the corresponding pin is configured as an output and the pin is not configured for alternate function operation.
0 = Drive a logical 0 (Low).
1= Drive a logical 1 (High). High value is not driven if the drain has been disabled by setting the corresponding Port Output Control register bit to 1.

LED Drive Enable Register

The LED Drive Enable register (Table 29) activates the controlled current drive. The Port C pin must first be enabled by setting the Alternate Function register to select the LED function.

Table 29. LED Drive Enable (LEDEN)

BITS	7	6	5	4	3	2	1	0
FIELD	LEDEN[7:0]							
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ADDR	F82H							

Timer Control Register Definitions

Timer 0–1 Control Registers

Time 0–1 Control Register 0

The Timer Control Register 0 (TxCTL0) and Timer Control Register 1 (TxCTL1) determine the timer operating mode (Table 48). It also includes a programmable PWM deadband delay, two bits to configure timer interrupt definition, and a status bit to identify if the most recent timer interrupt is caused by an input capture event.

Table 48. Timer 0–1 Control Register 0 (TxCTL0)

BITS	7	6	5	4	3	2	1	0
FIELD	TMODEHI	TICONFIG		Reserved	PWMD			INPCAP
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R
ADDR	F06H, F0EH							

TMODEHI—Timer Mode High Bit
This bit along with the TMODE field in TxCTL1 register determines the operating mode of the timer. This is the most significant bit of the Timer mode selection value. See the TxCTL1 register description for details of the full timer mode decoding.

TICONFIG—Timer Interrupt Configuration
This field configures timer interrupt definition.

0x = Timer Interrupt occurs on all defined Reload, Compare and Input Events
10 = Timer Interrupt only on defined Input Capture/Deassertion Events
11 = Timer Interrupt only on defined Reload/Compare Events

Reserved—Must be 0.

PWMD—PWM Delay value
This field is a programmable delay to control the number of system clock cycles delay before the Timer Output and the Timer Output Complement are forced to their active state.

000 = No delay
001 = 2 cycles delay
010 = 4 cycles delay
011 = 8 cycles delay
100 = 16 cycles delay
101 = 32 cycles delay

Caution: *The 24-bit WDT Reload Value must not be set to a value less than* `000004H`.

Table 58. Watchdog Timer Reload Upper Byte Register (WDTU)

BITS	7	6	5	4	3	2	1	0
FIELD	WDTU							
RESET	00H							
R/W	R/W*							
ADDR	FF1H							
R/W* - Read returns the current WDT count value. Write sets the appropriate Reload Value.								

WDTU—WDT Reload Upper Byte
Most-significant byte (MSB), Bits[23:16], of the 24-bit WDT reload value.

Table 59. Watchdog Timer Reload High Byte Register (WDTH)

BITS	7	6	5	4	3	2	1	0
FIELD	WDTH							
RESET	04H							
R/W	R/W*							
ADDR	FF2H							
R/W* - Read returns the current WDT count value. Write sets the appropriate Reload Value.								

WDTH—WDT Reload High Byte
Middle byte, Bits[15:8], of the 24-bit WDT reload value.

Table 60. Watchdog Timer Reload Low Byte Register (WDTL)

BITS	7	6	5	4	3	2	1	0
FIELD	WDTL							
RESET	00H							
R/W	R/W*							
ADDR	FF3H							
R/W* - Read returns the current WDT count value. Write sets the appropriate Reload Value.								

WDTL—WDT Reload Low

Least significant byte (LSB), Bits[7:0], of the 24-bit WDT reload value.

Infrared Encoder/Decoder

The Z8 Encore! XP® F082A Series products contain a fully-functional, high-performance UART to Infrared Encoder/Decoder (Endec). The Infrared Endec is integrated with an on-chip UART to allow easy communication between the Z8 Encore! and IrDA Physical Layer Specification, Version 1.3-compliant infrared transceivers. Infrared communication provides secure, reliable, low-cost, point-to-point communication between PCs, PDAs, cell phones, printers, and other infrared enabled devices.

Architecture

Figure 16 displays the architecture of the Infrared Endec.

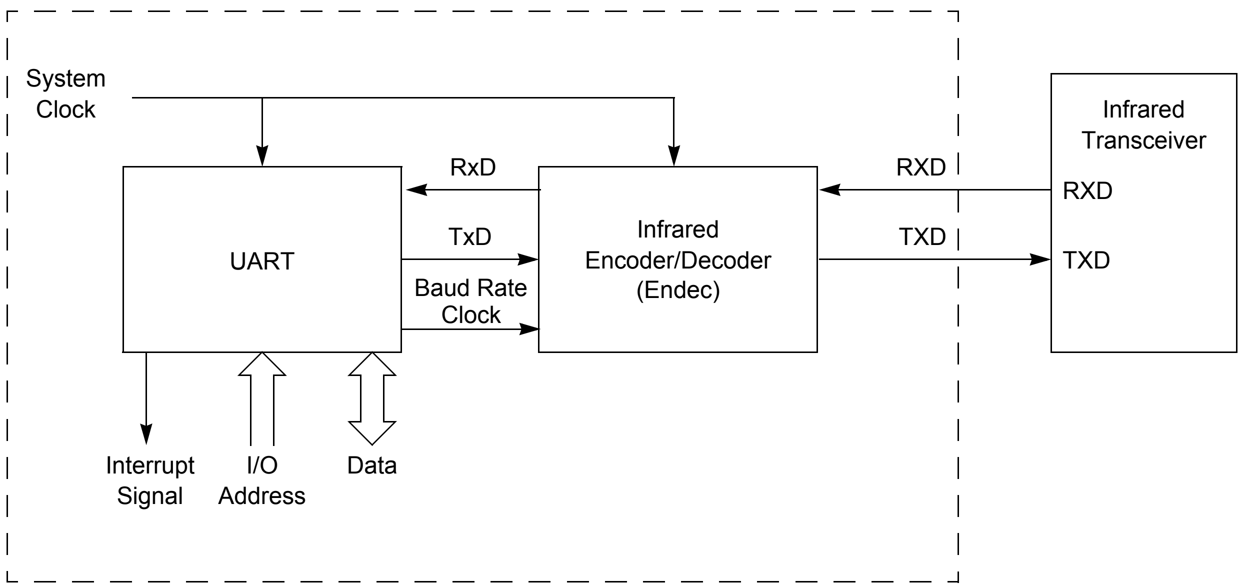


Figure 16. Infrared Data Communication System Block Diagram

Operation

When the Infrared Endec is enabled, the transmit data from the associated on-chip UART is encoded as digital signals in accordance with the IrDA standard and output to the infrared transceiver through the TXD pin. Likewise, data received from the infrared transceiver is passed to the Infrared Endec through the RXD pin, decoded by the Infrared

Analog-to-Digital Converter

The analog-to-digital converter (ADC) converts an analog input signal to its digital representation. The features of this sigma-delta ADC include:

- 11-bit resolution in DIFFERENTIAL mode.
- 10-bit resolution in SINGLE-ENDED mode.
- Eight single-ended analog input sources are multiplexed with general-purpose I/O ports.
- 9^{th} analog input obtained from temperature sensor peripheral.
- 11 pairs of differential inputs also multiplexed with general-purpose I/O ports.
- Low-power operational amplifier (LPO).
- Interrupt on conversion complete.
- Bandgap generated internal voltage reference with two selectable levels.
- Manual in-circuit calibration is possible employing user code (offset calibration).
- Factory calibrated for in-circuit error compensation.

Architecture

Figure 19 displays the major functional blocks of the ADC. An analog multiplexer network selects the ADC input from the available analog pins, ANA0 through ANA7.

The input stage of the ADC allows both differential gain and buffering. The following input options are available:

- Unbuffered input (SINGLE-ENDED and DIFFERENTIAL modes).
- Buffered input with unity gain (SINGLE-ENDED and DIFFERENTIAL modes).
- LPO output with full pin access to the feedback path.

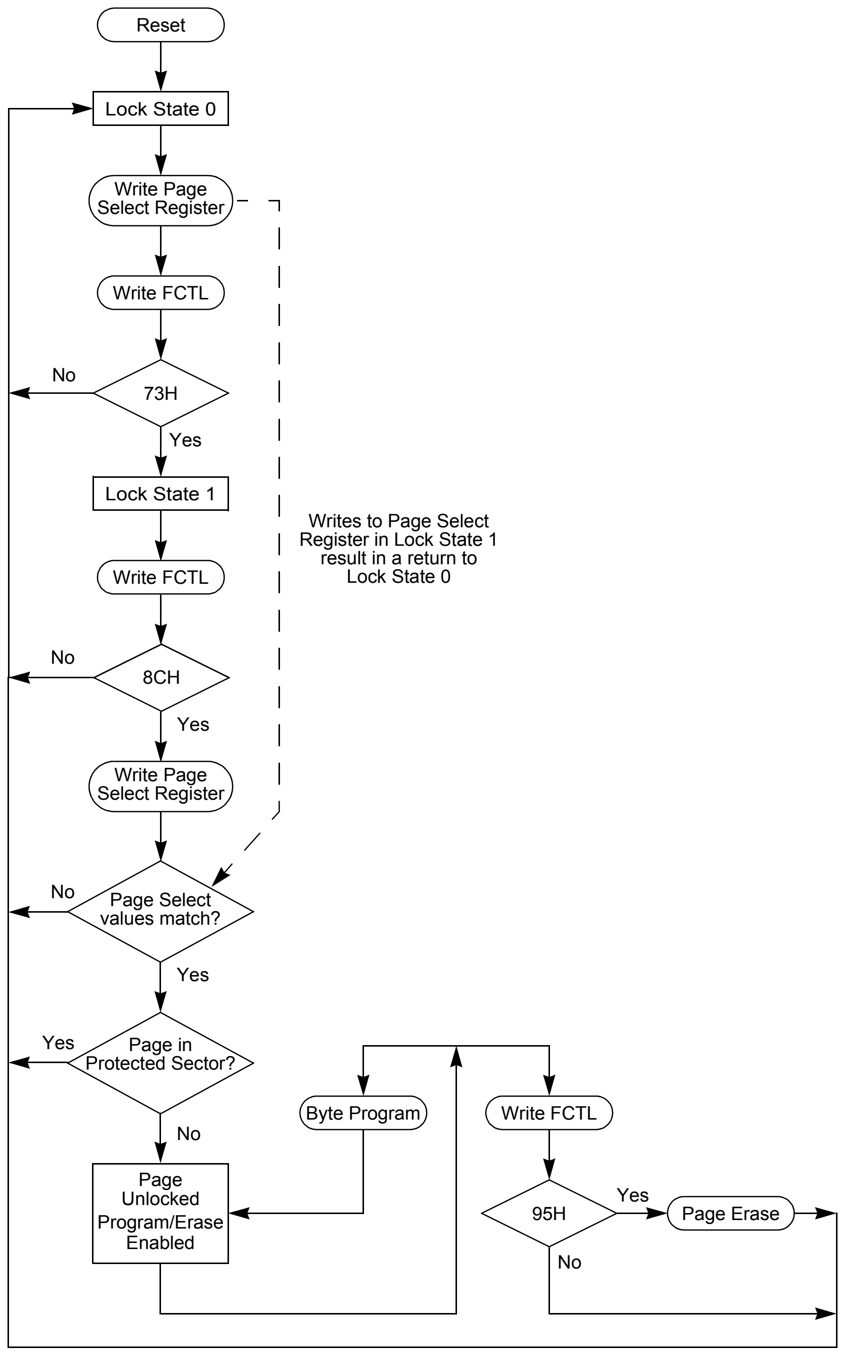


Figure 22. Flash Controller Operation Flow Chart

Flash Option Bits

Programmable Flash option bits allow user configuration of certain aspects of Z8 Encore! XP® F082A Series operation. The feature configuration data is stored in the Flash program memory and loaded into holding registers during Reset. The features available for control through the Flash Option Bits include:

- Watchdog Timer time-out response selection–interrupt or system reset
- Watchdog Timer always on (enabled at Reset)
- The ability to prevent unwanted read access to user code in Program Memory
- The ability to prevent accidental programming and erasure of all or a portion of the user code in Program Memory
- Voltage Brownout configuration-always enabled or disabled during STOP mode to reduce STOP mode power consumption
- Oscillator mode selection-for high, medium, and low power crystal oscillators, or external RC oscillator
- Factory trimming information for the internal precision oscillator and low voltage detection
- Factory calibration values for ADC, temperature sensor, and Watchdog Timer compensation
- Factory serialization and randomized lot identifier (optional)

Operation

Option Bit Configuration By Reset

Each time the Flash Option Bits are programmed or erased, the device must be Reset for the change to take effect. During any reset operation (System Reset, Power-On Reset, or Stop Mode Recovery), the Flash Option Bits are automatically read from the Flash Program Memory and written to Option Configuration registers. The Option Configuration registers control operation of the devices within the Z8 Encore! XP F082A Series. Option Bit control is established before the device exits Reset and the eZ8 CPU begins code execution. The Option Configuration registers are not part of the Register File and are not accessible for read or write access.

1 = Watchdog Timer is enabled upon execution of the WDT instruction. Once enabled, the Watchdog Timer can only be disabled by a Reset or Stop Mode Recovery. This setting is the default for unprogrammed (erased) Flash.

OSC_SEL[1:0]—Oscillator Mode Selection
00 = On-chip oscillator configured for use with external RC networks (<4 MHz).
01 = Minimum power for use with very low frequency crystals (32 kHz to 1.0 MHz).
10 = Medium power for use with medium frequency crystals or ceramic resonators (0.5 MHz to 5.0 MHz).
11 = Maximum power for use with high frequency crystals (5.0 MHz to 20.0 MHz). This setting is the default for unprogrammed (erased) Flash.

VBO_AO—Voltage Brownout Protection Always On
0 = Voltage Brownout Protection can be disabled in STOP mode to reduce total power consumption. For the block to be disabled, the power control register bit must also be written (see Power Control Register Definitions on page 34).
1 = Voltage Brownout Protection is always enabled including during STOP mode. This setting is the default for unprogrammed (erased) Flash.

FRP—Flash Read Protect
0 = User program code is inaccessible. Limited control features are available through the On-Chip Debugger.
1 = User program code is accessible. All On-Chip Debugger commands are enabled. This setting is the default for unprogrammed (erased) Flash.

Reserved—Must be 1.

FWP—Flash Write Protect
This Option Bit provides Flash Program Memory protection:
0 = Programming and erasure disabled for all of Flash Program Memory. Programming, Page Erase, and Mass Erase through User Code is disabled. Mass Erase is available using the On-Chip Debugger.
1 = Programming, Page Erase, and Mass Erase are enabled for all of Flash program memory.

Non-Volatile Data Storage

The Z8 Encore! XP® F082A Series devices contain a non-volatile data storage (NVDS) element of up to 128 bytes. This memory can perform over 100,000 write cycles.

Operation

The NVDS is implemented by special purpose Zilog® software stored in areas of program memory, which are not user-accessible. These special-purpose routines use the Flash memory to store the data. The routines incorporate a dynamic addressing scheme to maximize the write/erase endurance of the Flash.

Note: *Different members of the Z8 Encore! XP F082A Series feature multiple NVDS array sizes. See* Z8 Encore! XP® F082A Series Family Part Selection Guide *on page 3* *for details. Also the members containing 8 KB of Flash memory do not include the NVDS feature.*

NVDS Code Interface

Two routines are required to access the NVDS: a write routine and a read routine. Both of these routines are accessed with a CALL instruction to a pre-defined address outside of the user-accessible program memory. Both the NVDS address and data are single-byte values. Because these routines disturb the working register set, user code must ensure that any required working register values are preserved by pushing them onto the stack or by changing the working register pointer just prior to NVDS execution.

During both read and write accesses to the NVDS, interrupt service is NOT disabled. Any interrupts that occur during the NVDS execution must take care not to disturb the working register and existing stack contents or else the array may become corrupted. Disabling interrupts before executing NVDS operations is recommended.

Use of the NVDS requires 15 bytes of available stack space. Also, the contents of the working register set are overwritten.

For correct NVDS operation, the Flash Frequency Registers must be programmed based on the system clock frequency (see Flash Operation Timing Using the Flash Frequency Registers on page 145).

Byte Write

To write a byte to the NVDS array, the user code must first push the address, then the data byte onto the stack. The user code issues a `CALL` instruction to the address of the byte-write routine (0x10B3). At the return from the sub-routine, the write status byte

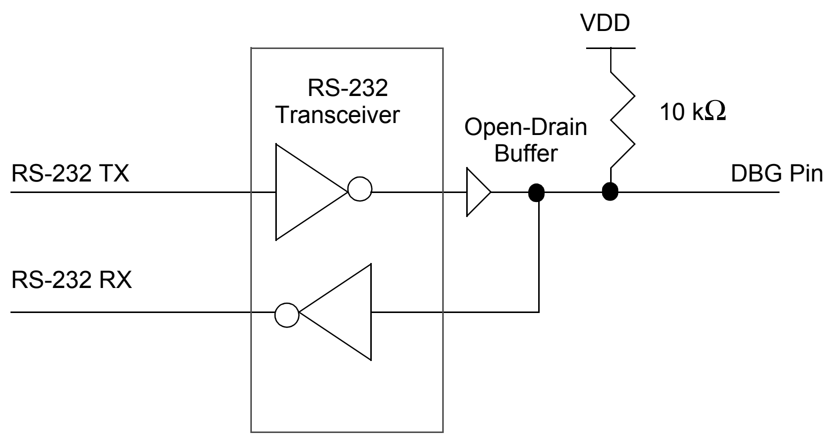


Figure 25. Interfacing the On-Chip Debugger's DBG Pin with an RS-232 Interface (2)

DEBUG Mode

The operating characteristics of the devices in DEBUG mode are:

- The eZ8 CPU fetch unit stops, idling the eZ8 CPU, unless directed by the OCD to execute specific instructions.
- The system clock operates unless in STOP mode.
- All enabled on-chip peripherals operate unless in STOP mode.
- Automatically exits HALT mode.
- Constantly refreshes the Watchdog Timer, if enabled.

Entering DEBUG Mode

The operating characteristics of the devices entering DEBUG mode are:

- The device enters DEBUG mode after the eZ8 CPU executes a BRK (Breakpoint) instruction.
- If the DBG pin is held Low during the final clock cycle of system reset, the part enters DEBUG mode immediately (20-/28-pin products only).

Note: *Holding the DBG pin Low for an additional 5000 (minimum) clock cycles after reset (making sure to account for any specified frequency error if using an internal oscillator) prevents a false interpretation of an Autobaud sequence (see* OCD Auto-Baud Detector/Generator *on page 176).*

```
DBG ← Size[15:8]
DBG ← Size[7:0]
DBG ← 1-65536 data bytes
```

- **Read Data Memory (0DH)**—The Read Data Memory command reads from Data Memory. This command is equivalent to the LDE and LDEI instructions. Data can be read 1 to 65536 bytes at a time (65536 bytes can be read by setting size to 0). If the device is not in DEBUG mode, this command returns `FFH` for the data.

```
DBG ← 0DH
DBG ← Data Memory Address[15:8]
DBG ← Data Memory Address[7:0]
DBG ← Size[15:8]
DBG ← Size[7:0]
DBG → 1-65536 data bytes
```

- **Read Program Memory CRC (0EH)**—The Read Program Memory CRC command computes and returns the Cyclic Redundancy Check (CRC) of Program Memory using the 16-bit CRC-CCITT polynomial. If the device is not in DEBUG mode, this command returns `FFFFH` for the CRC value. Unlike most other OCD Read commands, there is a delay from issuing of the command until the OCD returns the data. The OCD reads the Program Memory, calculates the CRC value, and returns the result. The delay is a function of the Program Memory size and is approximately equal to the system clock period multiplied by the number of bytes in the Program Memory.

```
DBG ← 0EH
DBG → CRC[15:8]
DBG → CRC[7:0]
```

- **Step Instruction (10H)**—The Step Instruction command steps one assembly instruction at the current Program Counter (PC) location. If the device is not in DEBUG mode or the Flash Read Protect Option bit is enabled, the OCD ignores this command.

```
DBG ← 10H
```

- **Stuff Instruction (11H)**—The Stuff Instruction command steps one assembly instruction and allows specification of the first byte of the instruction. The remaining 0-4 bytes of the instruction are read from Program Memory. This command is useful for stepping over instructions where the first byte of the instruction has been overwritten by a Breakpoint. If the device is not in DEBUG mode or the Flash Read Protect Option bit is enabled, the OCD ignores this command.

```
DBG ← 11H
DBG ← opcode[7:0]
```

- **Execute Instruction (12H)**—The Execute Instruction command allows sending an entire instruction to be executed to the eZ8 CPU. This command can also step over Breakpoints. The number of bytes to send for the instruction depends on the opcode.

Table 108. Oscillator Configuration and Selection

Clock Source	Characteristics	Required Setup
Internal Precision RC Oscillator	• 32.8 kHz or 5.53 MHz • High accuracy • No external components required	• Unlock and write Oscillator Control Register (OSCCTL) to enable and select oscillator at either 5.53 MHz or 32.8 kHz
External Crystal/ Resonator	• 32 kHz to 20 MHz • Very high accuracy (dependent on crystal or resonator used) • Requires external components	• Configure Flash option bits for correct external oscillator mode • Unlock and write OSCCTL to enable crystal oscillator, wait for it to stabilize and select as system clock (if the XTLDIS option bit has been de-asserted, no waiting is required)
External RC Oscillator	• 32 kHz to 4 MHz • Accuracy dependent on external components	• Configure Flash option bits for correct external oscillator mode • Unlock and write OSCCTL to enable crystal oscillator and select as system clock
External Clock Drive	• 0 to 20 MHz • Accuracy dependent on external clock source	• Write GPIO registers to configure PB3 pin for external clock function • Unlock and write OSCCTL to select external system clock • Apply external clock signal to GPIO
Internal Watchdog Timer Oscillator	• 10 kHz nominal • Low accuracy; no external components required • Very low power consumption	• Enable WDT if not enabled and wait until WDT Oscillator is operating. • Unlock and write Oscillator Control Register (OSCCTL) to enable and select oscillator

Caution: *Unintentional accesses to the oscillator control register can actually stop the chip by switching to a non-functioning oscillator. To prevent this condition, the oscillator control block employs a register unlocking/locking scheme.*

OSC Control Register Unlocking/Locking

To write the oscillator control register, unlock it by making two writes to the OSCCTL register with the values `E7H` followed by `18H`. A third write to the OSCCTL register changes the value of the actual register and returns the register to a locked state. Any other sequence of oscillator control register writes has no effect. The values written to unlock the register must be ordered correctly, but are not necessarily consecutive. It is possible to write to or read from other registers within the unlocking/locking operation.

Crystal Oscillator

The products in the Z8 Encore! XP® F082A Series contain an on-chip crystal oscillator for use with external crystals with 32 kHz to 20 MHz frequencies. In addition, the oscillator supports external RC networks with oscillation frequencies up to 4 MHz or ceramic resonators with frequencies up to 8 MHz. The on-chip crystal oscillator can be used to generate the primary system clock for the internal eZ8 CPU and the majority of the on-chip peripherals. Alternatively, the X_{IN} input pin can also accept a CMOS-level clock input signal (32 kHz–20 MHz). If an external clock generator is used, the X_{OUT} pin must be left unconnected. The Z8 Encore! XP F082A Series products do not contain an internal clock divider. The frequency of the signal on the X_{IN} input pin determines the frequency of the system clock.

Note: *Although the XIN pin can be used as an input for an external clock generator, the CLKIN pin is better suited for such use (see* System Clock Selection *on page 187**).*

Operating Modes

The Z8 Encore! XP F082A Series products support four oscillator modes:

- Minimum power for use with very low frequency crystals (32 kHz–1 MHz).
- Medium power for use with medium frequency crystals or ceramic resonators (0.5 MHz to 8 MHz).
- Maximum power for use with high frequency crystals (8 MHz to 20 MHz).
- On-chip oscillator configured for use with external RC networks (<4 MHz).

The oscillator mode is selected using user-programmable Flash Option Bits. See Flash Option Bits on page 153 for information.

Crystal Oscillator Operation

The Flash Option bit XTLDIS controls whether the crystal oscillator is enabled during reset. The crystal may later be disabled after reset if a new oscillator has been selected as the system clock. If the crystal is manually enabled after reset through the OSCCTL register, the user code must wait at least 1000 crystal oscillator cycles for the crystal to stabilize. After this, the crystal oscillator may be selected as the system clock.

Note: *The stabilization time varies depending on the crystal or resonator used, as well as on the feedback network. See Table 111 for transconductance values to compute oscillator stabilization times.*

Table 117. Bit Manipulation Instructions

Mnemonic	Operands	Instruction
BCLR	bit, dst	Bit Clear
BIT	p, bit, dst	Bit Set or Clear
BSET	bit, dst	Bit Set
BSWAP	dst	Bit Swap
CCF	—	Complement Carry Flag
RCF	—	Reset Carry Flag
SCF	—	Set Carry Flag
TCM	dst, src	Test Complement Under Mask
TCMX	dst, src	Test Complement Under Mask using Extended Addressing
TM	dst, src	Test Under Mask
TMX	dst, src	Test Under Mask using Extended Addressing

Table 118. Block Transfer Instructions

Mnemonic	Operands	Instruction
LDCI	dst, src	Load Constant to/from Program Memory and Auto-Increment Addresses
LDEI	dst, src	Load External Data to/from Data Memory and Auto-Increment Addresses

Table 119. CPU Control Instructions

Mnemonic	Operands	Instruction
ATM	—	Atomic Execution
CCF	—	Complement Carry Flag
DI	—	Disable Interrupts
EI	—	Enable Interrupts
HALT	—	Halt Mode
NOP	—	No Operation
RCF	—	Reset Carry Flag

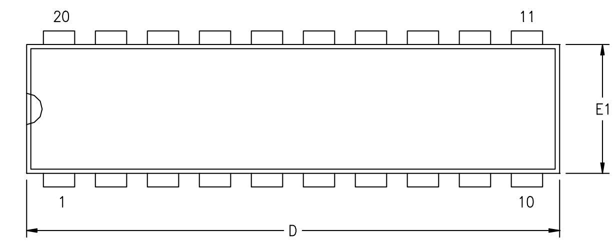
On-Chip Peripheral AC and DC Electrical Characteristics

Table 131. Power-On Reset and Voltage Brownout Electrical Characteristics and Timing

		T_A = -40 °C to +105 °C				
Symbol	Parameter	Minimum	Typical[1]	Maximum	Units	Conditions
V_{POR}	Power-On Reset Voltage Threshold	2.20	2.45	2.70	V	$V_{DD} = V_{POR}$
V_{VBO}	Voltage Brownout Reset Voltage Threshold	2.15	2.40	2.65	V	$V_{DD} = V_{VBO}$
	V_{POR} to V_{VBO} hysteresis		50	75	mV	
	Starting V_{DD} voltage to ensure valid Power-On Reset.	–	V_{SS}	–	V	
T_{ANA}	Power-On Reset Analog Delay	–	70	–	µs	$V_{DD} > V_{POR}$; T_{POR} Digital Reset delay follows T_{ANA}
T_{POR}	Power-On Reset Digital Delay		16		µs	66 Internal Precision Oscillator cycles + IPO startup time (T_{IPOST})
T_{POR}	Power-On Reset Digital Delay		1		ms	5000 Internal Precision Oscillator cycles
T_{SMR}	Stop Mode Recovery with crystal oscillator disabled		16		µs	66 Internal Precision Oscillator cycles
T_{SMR}	Stop Mode Recovery with crystal oscillator enabled		1		ms	5000 Internal Precision Oscillator cycles
T_{VBO}	Voltage Brownout Pulse Rejection Period	–	10	–	µs	Period of time in which $V_{DD} < V_{VBO}$ without generating a Reset.
T_{RAMP}	Time for V_{DD} to transition from V_{SS} to V_{POR} to ensure valid Reset	0.10	–	100	ms	
T_{SMP}	Stop Mode Recovery pin pulse rejection period		20		ns	For any SMR pin or for the Reset pin when it is asserted in STOP mode.

[1]Data in the typical column is from characterization at 3.3 V and 30 °C. These values are provided for design guidance only and are not tested in production.

Figure 42 displays the 20-pin Plastic Dual Inline Package (PDIP) available for the Z8 Encore! XP F082A Series devices.



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.38	0.81	.015	.032
A2	3.25	3.68	.128	.145
B	0.41	0.51	.016	.020
B1	1.47	1.57	.058	.062
C	0.20	0.30	.008	.012
D	25.65	26.16	1.010	1.030
E	7.49	8.26	.295	.325
E1	6.10	6.65	.240	.262
$\boxed{e}$	2.54 BSC		.100 BSC	
eA	7.87	9.14	.310	.360
L	3.18	3.43	.125	.135
Q1	1.42	1.65	.056	.065
S	1.52	1.65	.060	.065

CONTROLLING DIMENSIONS : INCH

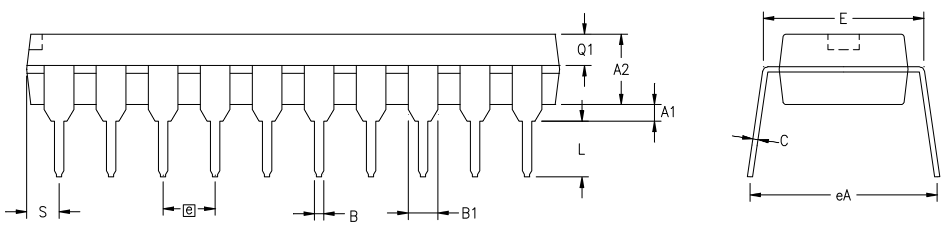


Figure 42. 20-Pin Plastic Dual Inline Package (PDIP)

Part Number Suffix Designations

Z8 F 04 2A S H 020 S C

Environmental Flow
C = Standard Plastic Packaging Compound
G = Green Plastic Packaging Compound

Temperature Range
S = Standard, 0 °C to 70 °C
E = Extended, -40 °C to +105 °C

Speed
020 = 20 MHz

Pin Count
B = 8
H = 20
J = 28

Package
H = SSOP
P = PDIP
Q = QFN
S = SOIC

Device Type
2A = Contains Advanced Analog Peripherals
1A = Does Not Contain Advanced Analog Peripherals

Memory Size
08 = 8 KB Flash, 1 KB RAM, 0 B NVDS
04 = 4 KB Flash, 1 KB RAM, 128 B NVDS
02 = 2 KB Flash, 512 B RAM, 64 B NVDS
01 = 1 KB Flash, 256 B RAM, 16 B NVDS

Memory Type
F = Flash

Device Family
Z8 = Zilog's 8-Bit Microcontroller